

# ELM5964-4PS

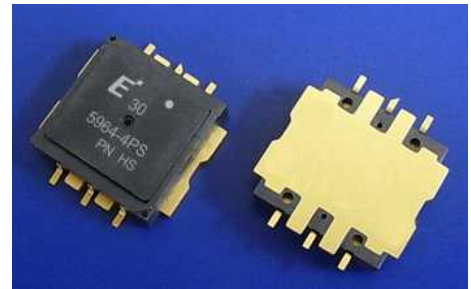
C-Band Internally Matched FET

## ● FEATURES

High Output Power: P1dB=36.0dBm (Typ.)  
High Gain: G1dB=11.5dB (Typ.)  
High PAE:  $\eta_{add}$ =37% (Typ.)  
Frequency Band: 5.9~6.4GHz  
Internally matched  
Plastic Package for SMT applications

## ● DESCRIPTION

The ELM5964-4PS is a power GaAs FET that is internally matched for standard communication bands to provide optimum power and gain.



### ABSOLUTE MAXIMUM RATING (Case Temperature Tc=25 deg-C)

Item	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DS</sub>	15	V
Gate-Source Voltage	V <sub>GS</sub>	-5	V
Total Power Dissipation	P <sub>T</sub>	27.3	W
Storage Temperature	T <sub>STG</sub>	-40 to +125	deg-C
Channel Temperature	T <sub>CH</sub>	175	deg-C

### RECOMMENDED OPERATING CONDITION (Case Temperature Tc=25 deg-C)

Item	Symbol	Condition	Limit	Unit
DC Input Voltage	V <sub>DS</sub>		<10	V
Forward Gate Current	I <sub>GF</sub>	R <sub>G</sub> =100 ohm	<+16	mA
Reverse Gate Current	I <sub>GR</sub>	R <sub>G</sub> =100 ohm	>-2.2	mA
Channel Temperature	T <sub>CH</sub>		155	deg-C

### ELECTRICAL CHARACTERISTICS (Case Temperature Tc=25 deg-C)

Item	Symbol	Condition	Limit			Unit	
			Min.	Typ.	Max.		
Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =5V, V <sub>GS</sub> =0V	-	1700	2600	mA	
Trans conductance	gm	V <sub>DS</sub> =5V, I <sub>DS</sub> =1100mA	-	1700	-	mS	
Pinch-off Voltage	V <sub>P</sub>	V <sub>DS</sub> =5V, I <sub>DS</sub> =85mA	-0.5	-1.5	-3.0	V	
Gate-Source Breakdown Voltage	V <sub>GSO</sub>	I <sub>GS</sub> =85uA	-5.0	-	-	V	
Output Power at 1dB G.C.P.	P <sub>1dB</sub>	V <sub>DS</sub> =10V I <sub>ds(DC)</sub> =0.65I <sub>DSS</sub> (typ.) f=5.9~6.4 GHz	35.0	36.0	-	dBm	
Power Gain at 1dB G.C.P.	G <sub>1dB</sub>		10.0	11.5	-	dB	
Drain Current	I <sub>dSr</sub>		-	1100	1300	mA	
Power Added Efficiency	$\eta_{add}$		-	37	-	%	
Gain Flatness	$\Delta G$		-	-	1.2	dB	
3 <sup>rd</sup> Order Inter Modulation Distortion	IM <sub>3</sub>		f=6.4GHz $\Delta f$ =10MHz, 2-tone Test Pout=25.5dBm (S.C.L.)	-40	-43	-	dBc
R <sub>th</sub>	R <sub>th</sub>		Channel to Case	-	4.5	5.5	Deg-C/W
$\Delta T_{ch}$	$\Delta T_{ch}$	10V x I <sub>dSr</sub> x R <sub>th</sub>	-	-	71.5	Deg-C	

**Eudyna**

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C-Band Internally Matched FET

## CASE STYLE: I2C

ESD	Class 3 A	4000-8000V
MSL	2A	4 weeks after open the package

## Ordering Information

Model Type	MOQ	MOU	Packing Style
ELM5964-4PS	15pcs	15pcs	15pcs Tray
ELM5964-4PST	500pcs	500pcs	24mm width Tape (500pcs/Reel)

\*MOQ stands for Minimum Order Quantity.

\*MOU stands for Minimum Order Unit size.

## Note

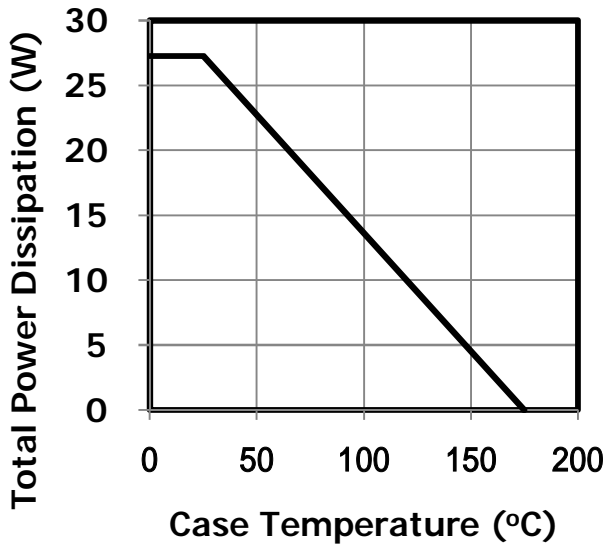
- This device will not be delivered with test data but tested pass/fail 100% against DC and RF specifications.
- NO liquid cleaning process is suitable for this device. (including de-ionized water or solvent)

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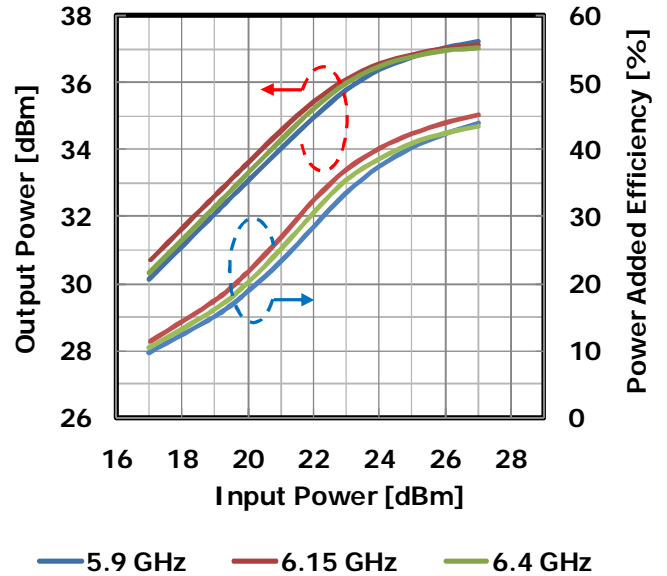
- RF Characteristics

Power Derating Curve



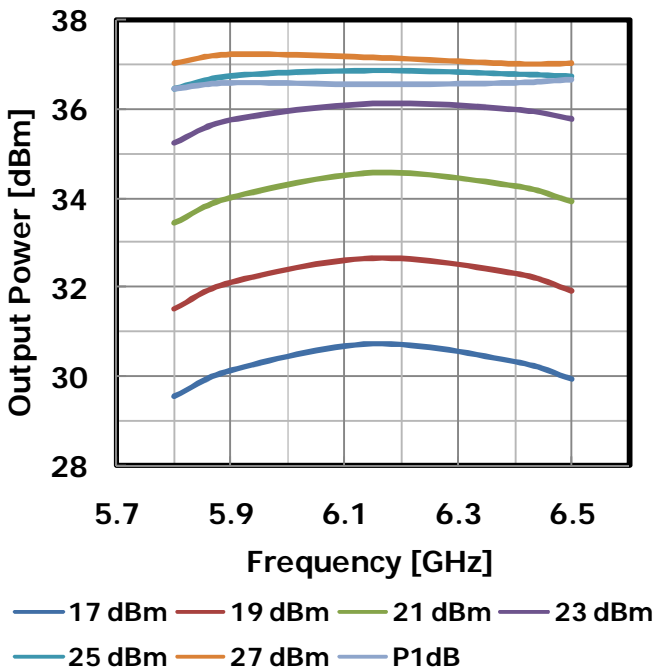
Input Power vs. Output Power, Power Added Efficiency

$V_{DS}=10V, I_{DS(DC)}=1100mA$



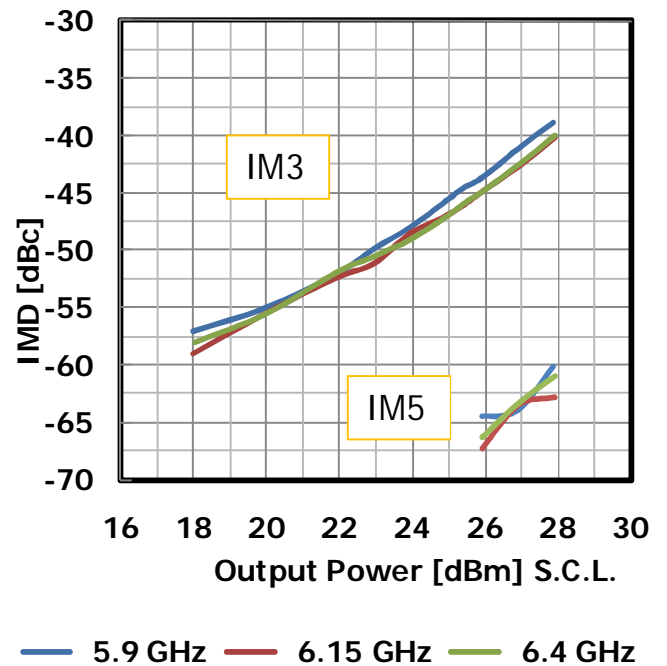
Output Power vs. Frequency

$V_{DS}=10V, I_{DS(DC)}=1100mA$



IMD vs. Output Power

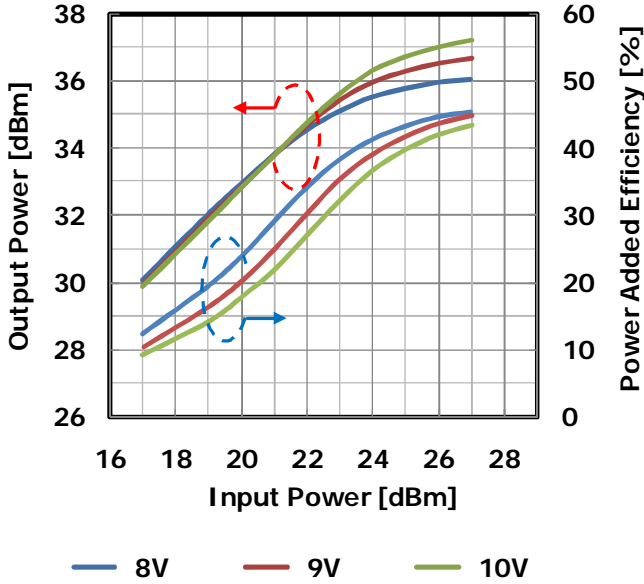
$V_{DS}=10V, I_{DS(DC)}=1100mA$



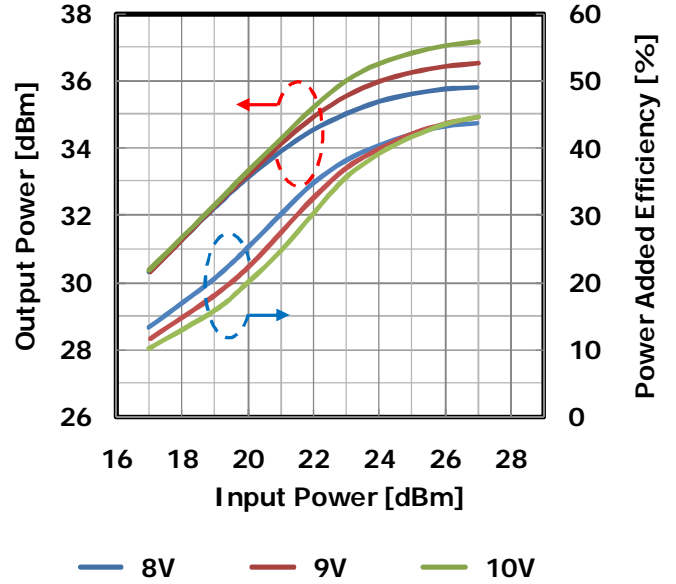
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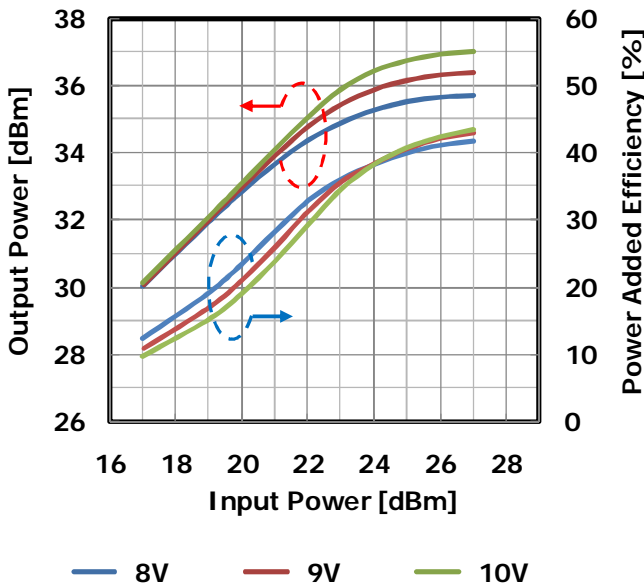
Input Power vs. Output Power, Power Added Efficiency by Drain Voltage  
 $I_{DS(DC)} = 1100\text{mA}$  @5.9GHz



Input Power vs. Output Power, Power Added Efficiency by Drain Voltage  
 $I_{DS(DC)} = 1100\text{mA}$  @6.15GHz



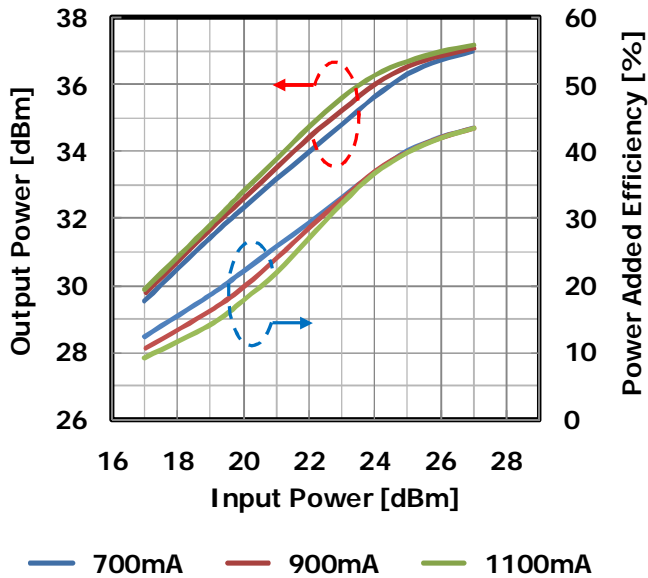
Input Power vs. Output Power, Power Added Efficiency by Drain Voltage  
 $I_{DS(DC)} = 1100\text{mA}$  @6.4GHz



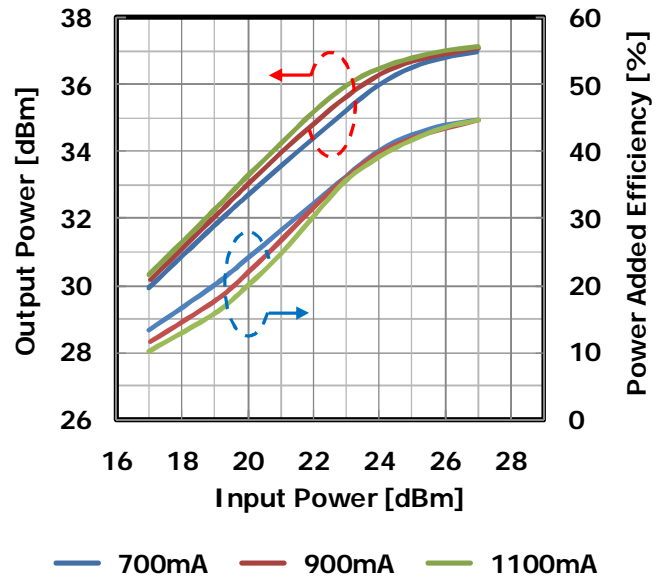
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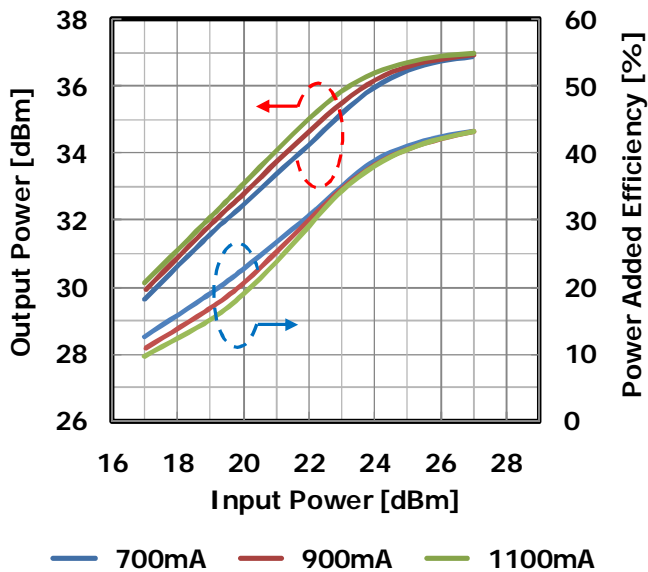
Input Power vs. Output Power, Power Added Efficiency by Quiescent Drain Current  
 $V_{DS}=10V$  @5.9GHz



Input Power vs. Output Power, Power Added Efficiency by Quiescent Drain Current  
 $V_{DS}=10V$  @6.15GHz



Input Power vs. Output Power, Power Added Efficiency by Quiescent Drain Current  
 $V_{DS}=10V$  @6.4GHz

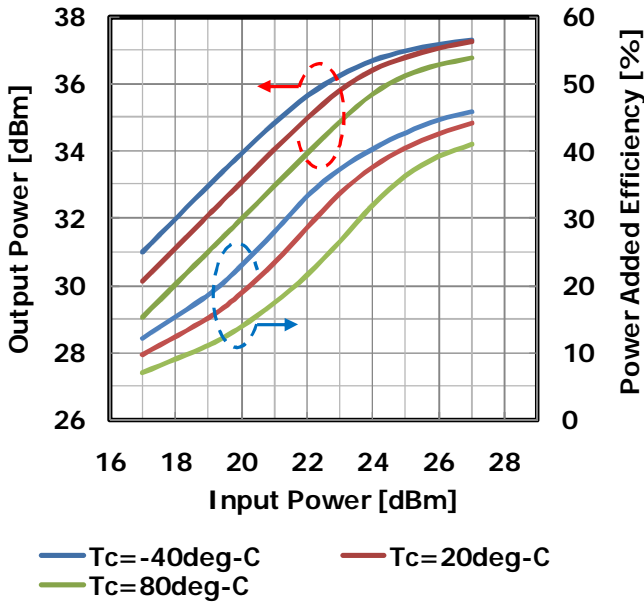


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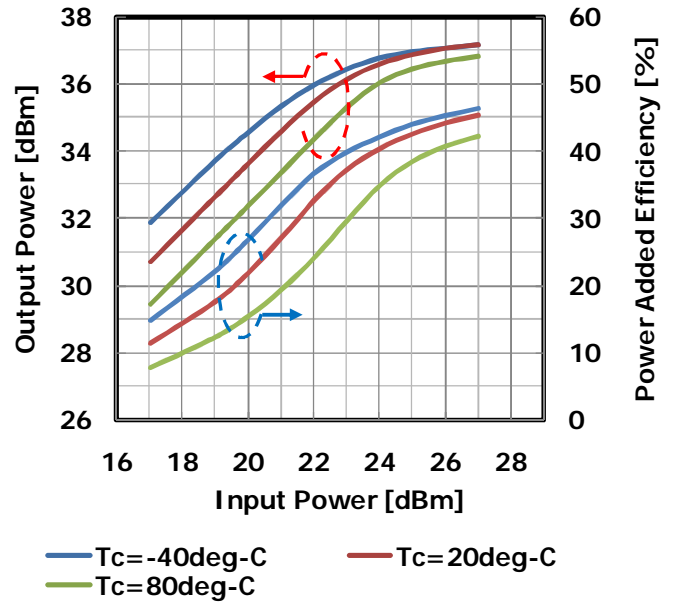
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C-Band Internally Matched FET

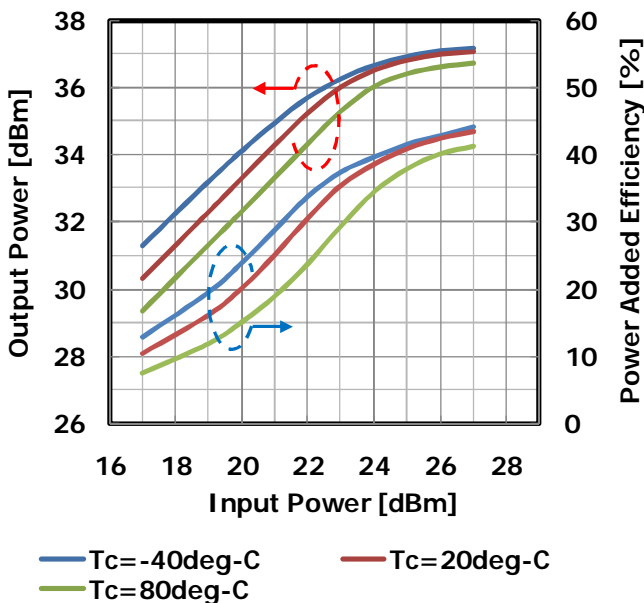
Input Power vs. Output Power, Power Added Efficiency by Temperature  
 $V_{DS}=10V$  @5.9GHz



Input Power vs. Output Power, Power Added Efficiency by Temperature  
 $V_{DS}=10V$  @6.15GHz



Input Power vs. Output Power, Power Added Efficiency by Temperature  
 $V_{DS}=10V$  @6.4GHz

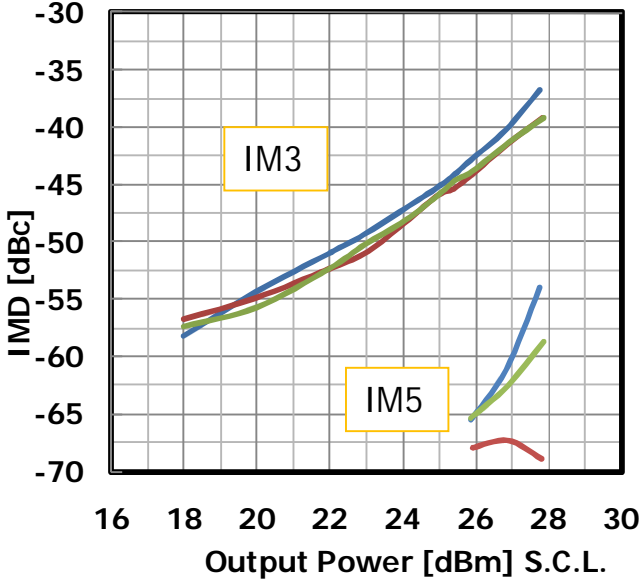


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C-Band Internally Matched FET

IMD Performance vs. Output Power by Drain Voltage

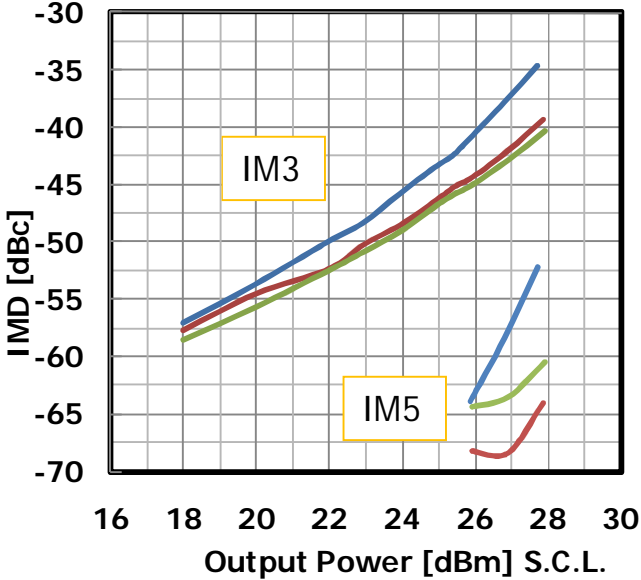
$I_{DS(DC)} = 1100\text{mA}$  @5.9GHz



8V 9V 10V

IMD Performance vs. Output Power by Drain Voltage

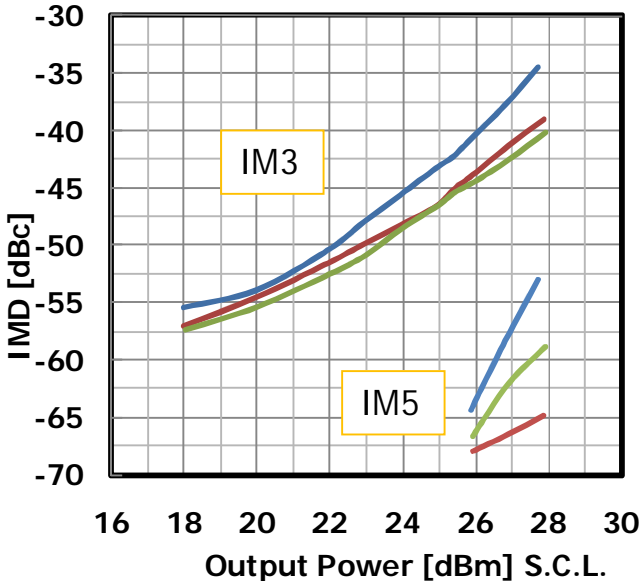
$I_{DS(DC)} = 1100\text{mA}$  @6.15GHz



8V 9V 10V

IMD Performance vs. Output Power by Drain Voltage

$I_{DS(DC)} = 1100\text{mA}$  @6.4GHz



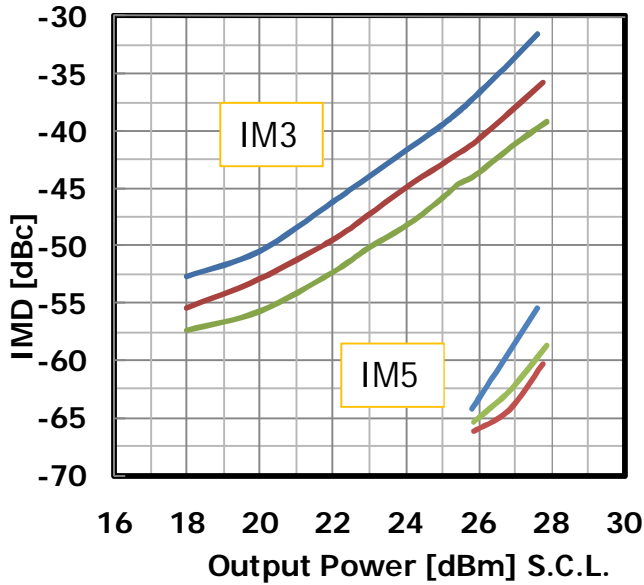
8V 9V 10V



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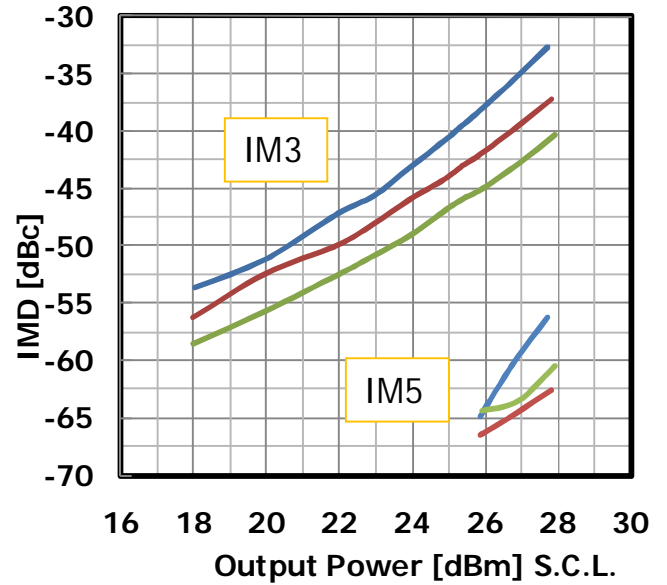
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IMD Performance vs. Output Power by Quiescent Drain Current  
 $V_{DS}=10V$  @5.9GHz



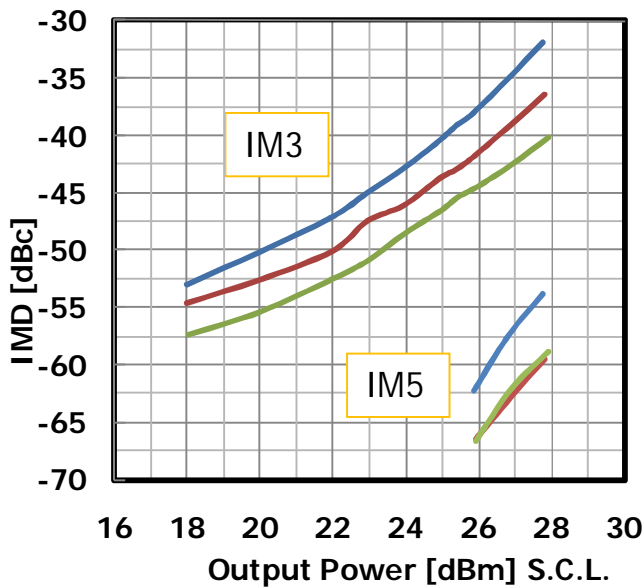
— 700mA — 900mA — 1100mA

IMD Performance vs. Output Power by Quiescent Drain Current  
 $V_{DS}=10V$  @6.15GHz



— 700mA — 900mA — 1100mA

IMD Performance vs. Output Power by Quiescent Drain Current  
 $V_{DS}=10V$  @6.4GHz



— 700mA — 900mA — 1100mA

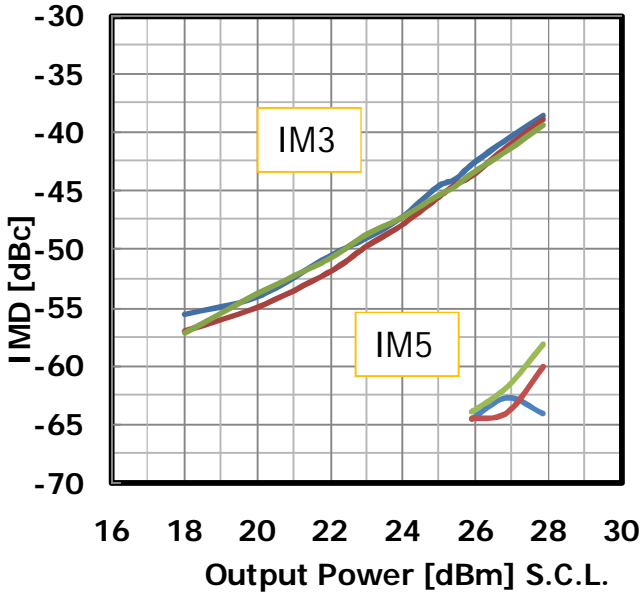




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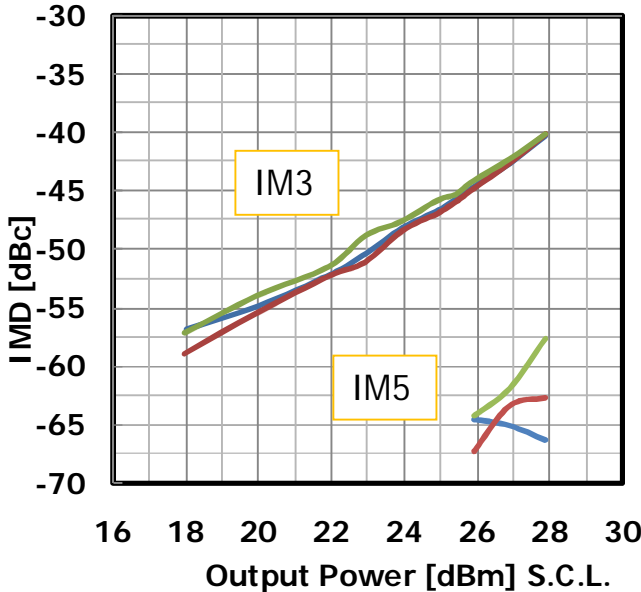
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IMD Performance vs. Output Power by Temperature  
 $V_{DS}=10V$  @5.9GHz



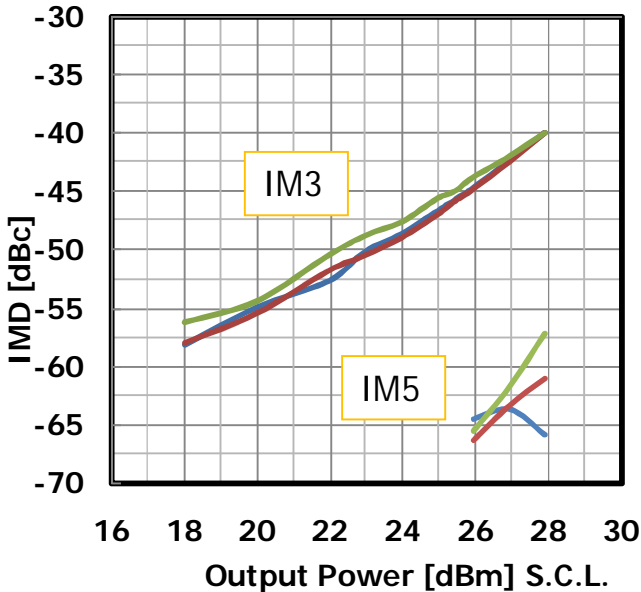
— Tc=-40deg-C      — Tc=20deg-C  
 — Tc=80deg-C

IMD Performance vs. Output Power by Temperature  
 $V_{DS}=10V$  @6.15GHz



— Tc=-40deg-C      — Tc=20deg-C  
 — Tc=80deg-C

IMD Performance vs. Output Power by Temperature  
 $V_{DS}=10V$  @6.4GHz



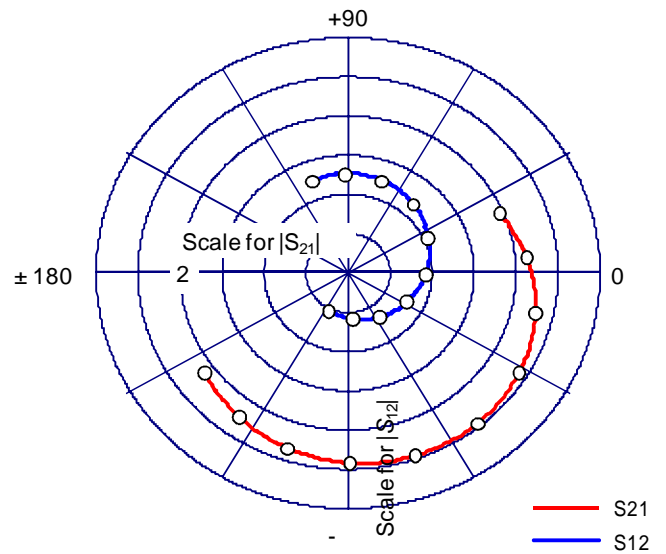
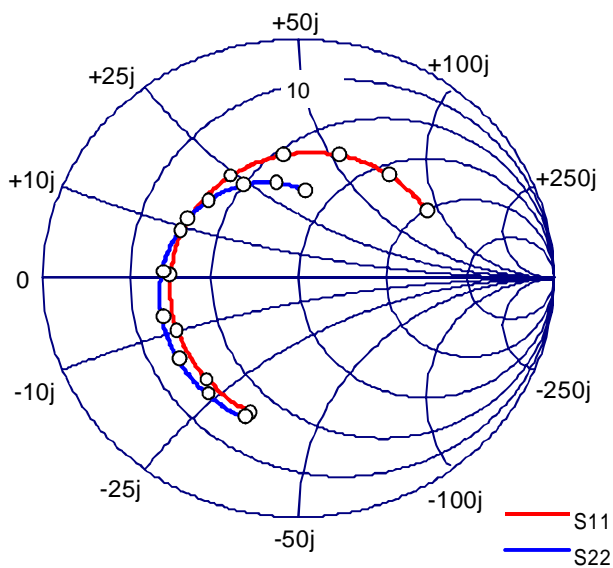
— Tc=-40deg-C      — Tc=20deg-C  
 — Tc=80deg-C



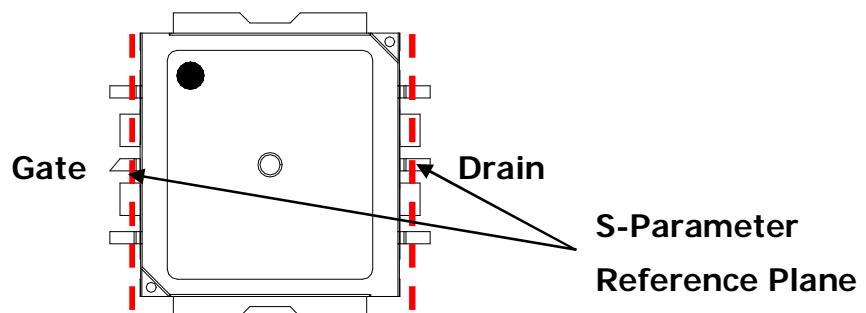
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## ● S-Parameter



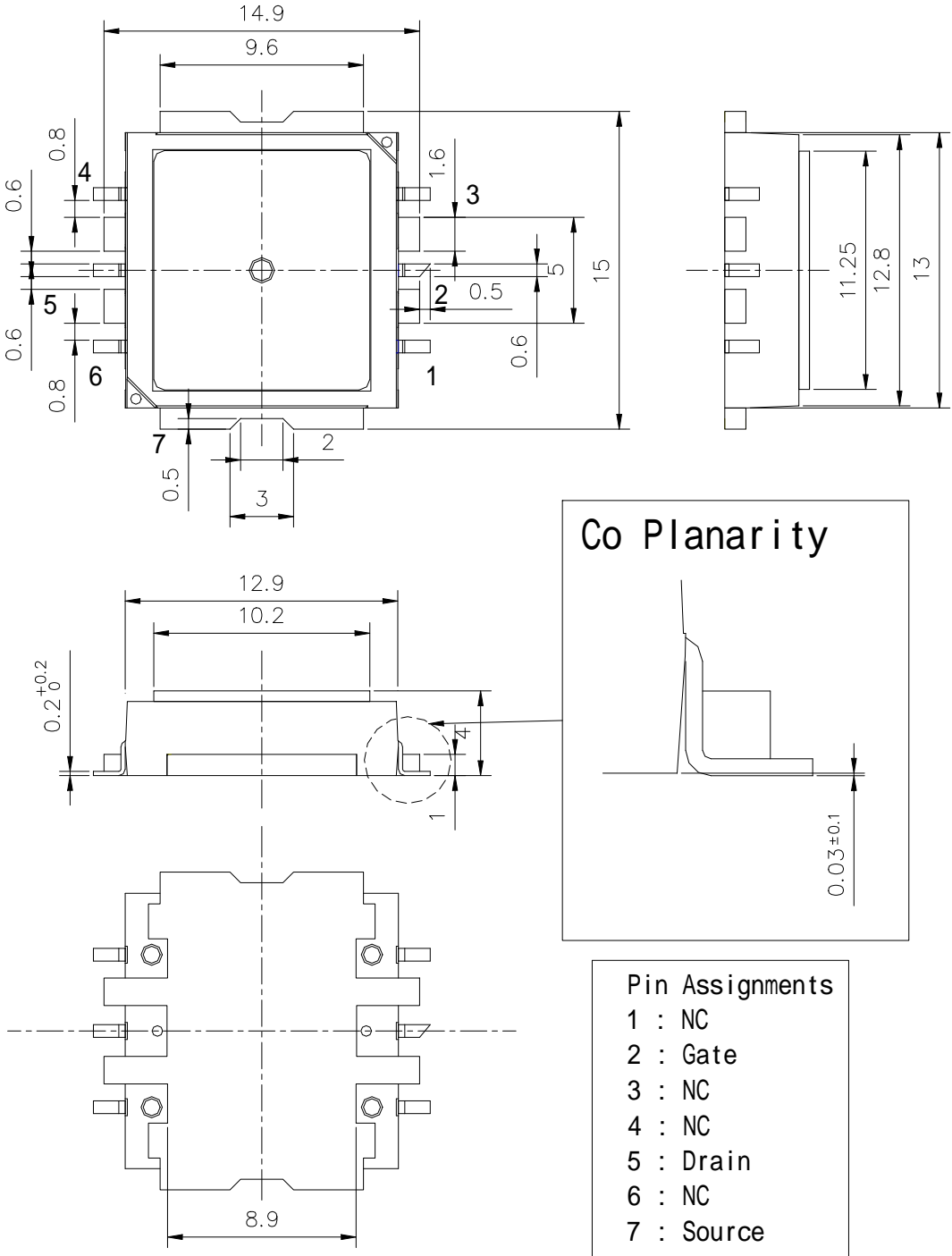
Frequency (MHz)	S11		S21		S12		S22	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
5700	0.567	-121.1	4.260	20.5	0.046	106.0	0.574	-124.0
5800	0.555	-146.1	4.318	2.2	0.043	86.3	0.581	-144.0
5900	0.552	-169.8	4.269	-15.4	0.039	66.7	0.593	-162.5
6000	0.556	168.9	4.155	-32.1	0.035	47.1	0.605	-178.6
6100	0.562	150.0	4.018	-47.4	0.031	27.1	0.610	167.5
6200	0.567	132.1	3.894	-62.7	0.026	5.8	0.613	155.2
6300	0.569	116.3	3.816	-76.9	0.023	-15.3	0.614	144.7
6400	0.567	100.8	3.775	-90.9	0.020	-38.5	0.602	135.4
6500	0.560	84.8	3.792	-104.9	0.019	-62.4	0.580	127.0
6600	0.551	66.6	3.833	-120.0	0.018	-90.4	0.542	118.7



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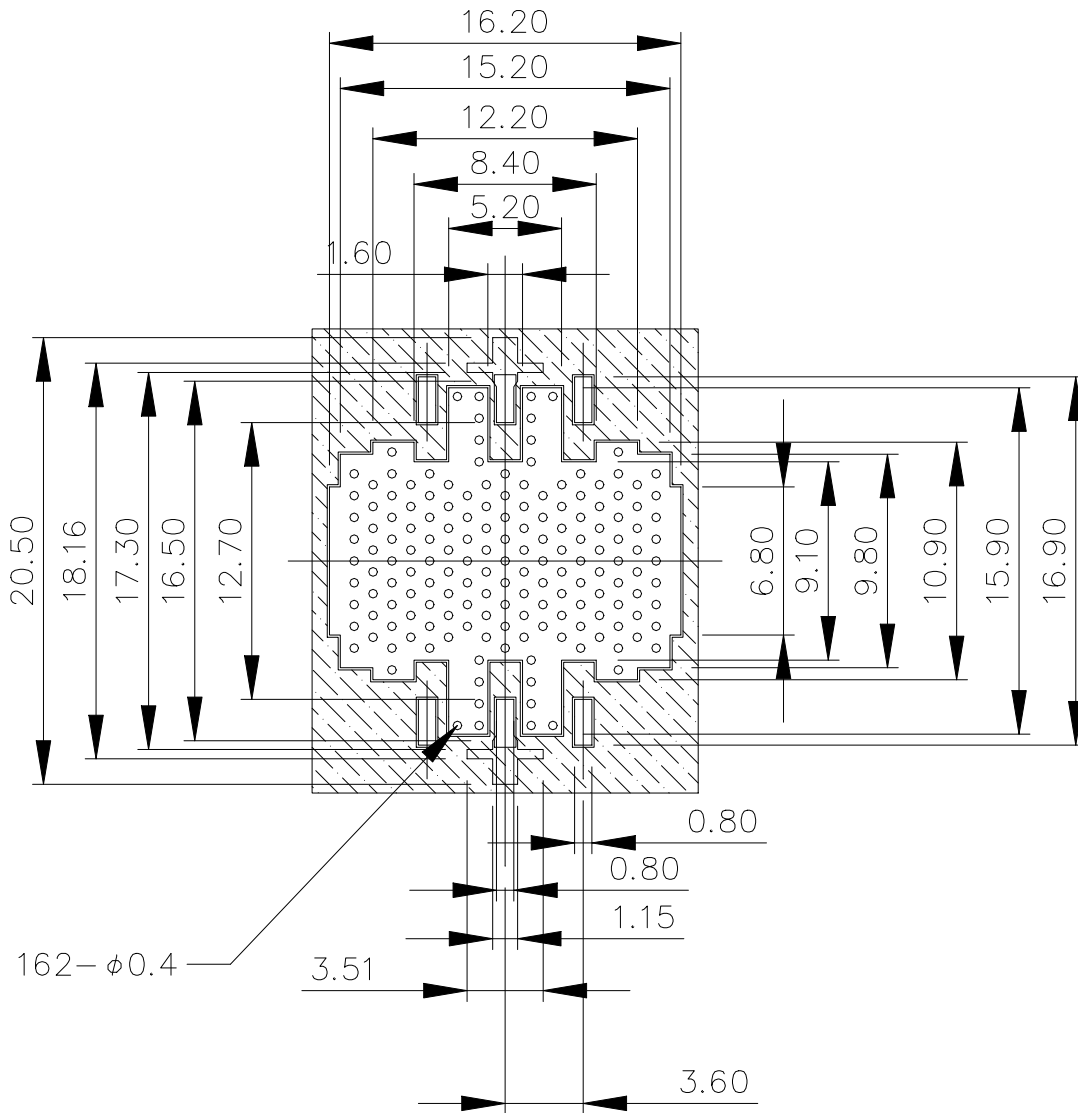
● Package Outline



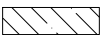
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## ● PCB Pads and Solder-Resist Pattern



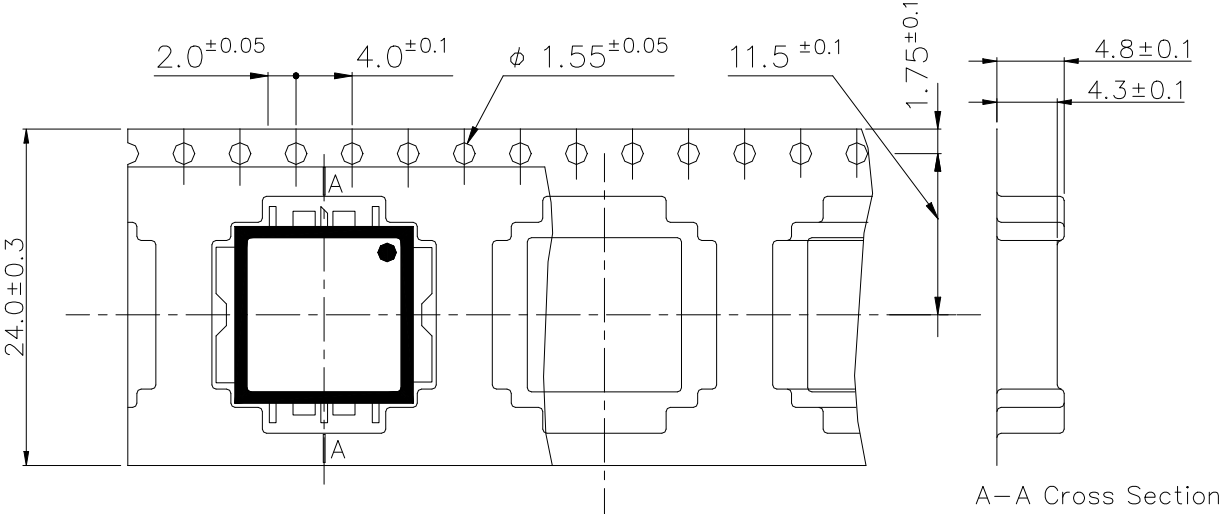
Notes :

1. Laminate : Rogers Corporation R04003, Thickness  $t=0.508\text{mm}$ , Cu Foil  $18\mu\text{m}$ .  
Finish to copper foil : Ni  $0.1\mu\text{m}$  min. / Au  $0.1\mu\text{m}$  (Both side).
2.  : Resist

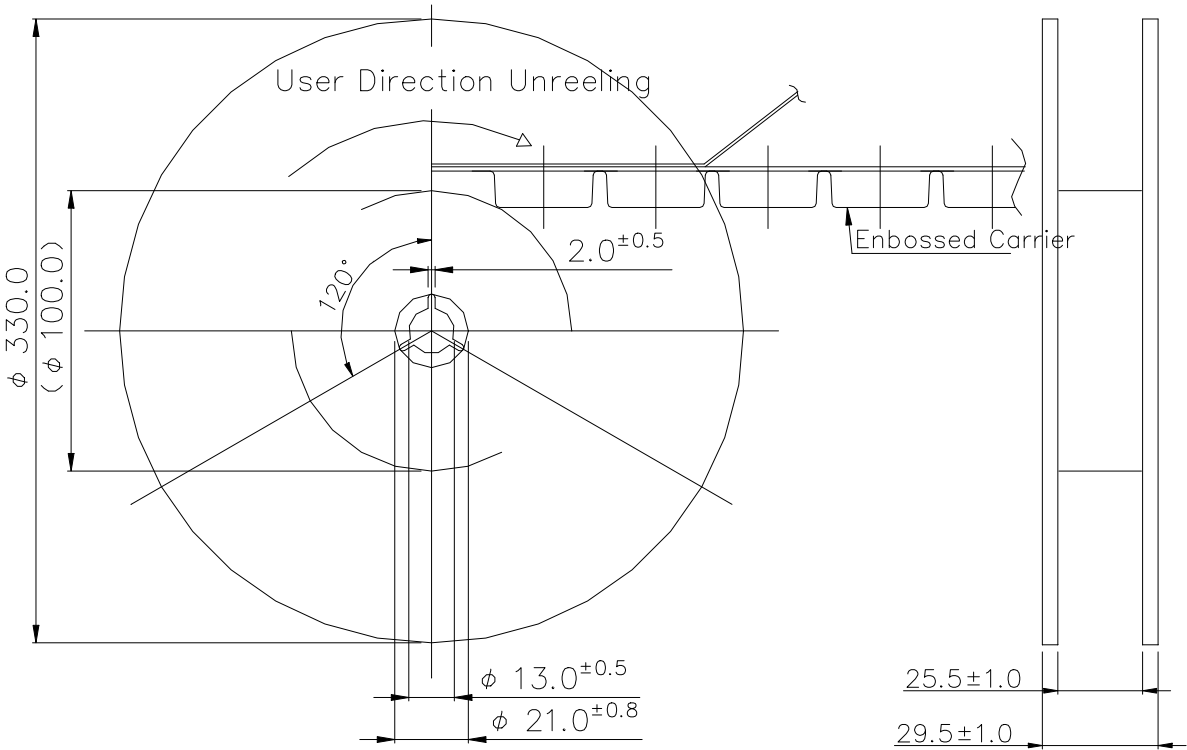
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- **Marking and Tape/Reel Configuration**



A-A Cross Section



Quantity: 500pcs/tape  
Tape Material: Conductive PS

(unit in mm)



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## ● Mounting Instructions for Package for Lead-free solder

### Mounting Condition

For soldering, Lead-free solder (Sn-3.0Ag-0.5Cu)\*1 or equivalent shall be used.

1. The example solder is a tin-rich alloy with 3.0% silver and 0.5% copper, often called Sn 96 for its approximate Tin content.
2. A rosin type flux with chlorine content of 0.2% or less shall be used. The rosin flux with low halogen content is recommended. When soldering, use the following time/ temperature profile with any of the methods listed for acceptable solder joints.
3. Make sure the devices have been properly prepared with flux prior soldering.

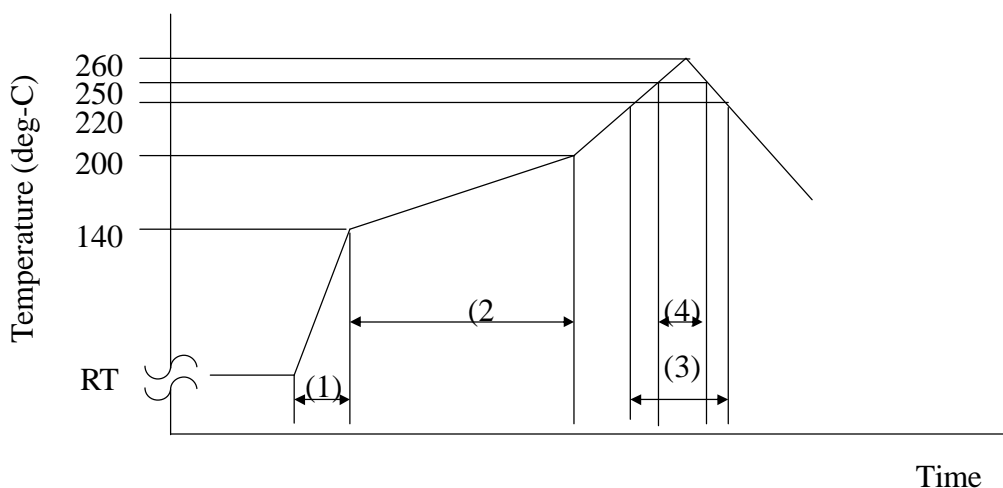
### \*Reflow soldering method (Infrared reflow / Heat circulation reflow / Hot plate reflow):

Limit solder to 3 reflow cycles because resin is used in the modules manufacturing process.

Excessive reflow will affect the resin resulting in a potential failure or latent defect.

The recommended reflow temperature profile is shown below. The temperature of the reflow profile must be measured at the device lead.

### ● Reflow temperature profile and condition:



- |                        |   |
|------------------------|---|
| (1). Temperature rise: | 3 deg-C/seconds.  |
| (2). Preheating:       | 150 – 200 deg-C, 60 - 180seconds.                         |
| (3). Main heating:     | 220 deg-C, 60 seconds max.                                |
| (4). Main heating:     | 260 deg-C max., more than 250 deg-C, 20 - 40 seconds max. |

\* Measurement point: Device Heat-sink (Source Pin).

1. The above-recommended conditions were confirmed using the manufacturer's equipment and materials. However, when soldering these products, the soldering condition should be verified by customer using their own particular equipment and materials.

### ● Cleaning

Avoid washing of the device after soldering by reflow method due to the risk of liquid absorption by the resin used in this part.

## Humidity Lifetime for ELMxxxx-4PST

The following graph shows the effect of moisture on lifetime (moisture resistance) for the **ELMxxxx-4PST**. Each graph indicates the MTTF and failure rate prediction (Confidential Level = 90 %) which calculated from the results of highly accelerated temperature and humidity stress test (HAST).

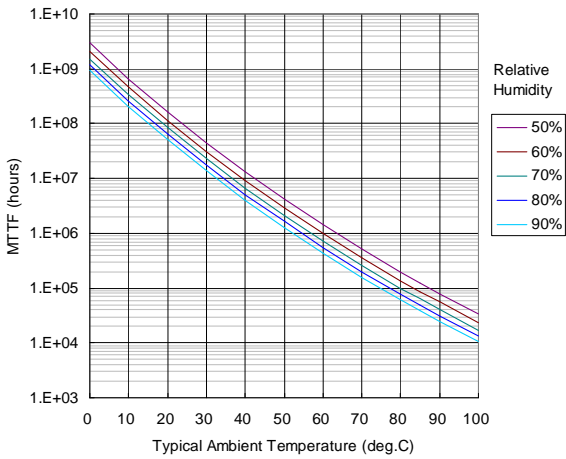
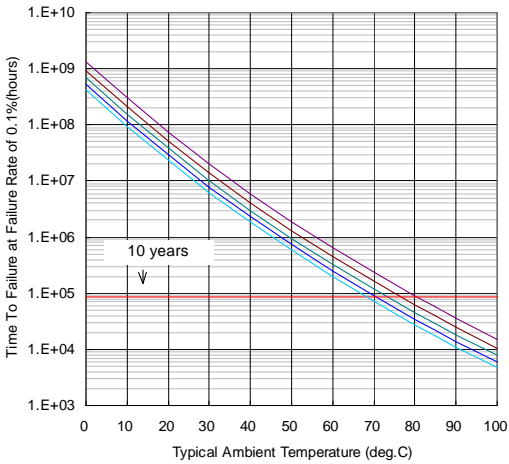
Representative of device type: ELM7179-4PST

Subject of device type : ELMxxxx-4PST

### Field environmental conditions for operation

If the **ELMxxxx-4PST** is installed in a non-hermetic environment, please refer to the following recommendations and notes for design with, and assembly and use of our products.

- Note 1. When drain current cuts off, it should be cut off by drain bias, and not cut off by gate bias only. The humidity lifetime becomes shorter in case of the gate-only cut off operation due to electric field strength interacting with humidity.
- Note 2. **ELMxxxx-4PST** should be used under the environment conditions of no dew condensation. These plots do not apply in the case of liquid absorbed into the resin, whether applied to the part in assembly or as condensate in the application.



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C-Band Internally Matched FET

## For further information please contact:

### Eudyna Devices USA Inc.

2355 Zanker Rd.  
San Jose, CA 95131-1138, U.S.A.  
TEL: +1 408 232-9500  
FAX: +1 408 428-9111

### Eudyna Devices Europe Ltd.

150 Edinburgh Avenue  
Slough, Berkshire, SL1 4SS  
United Kingdom  
TEL: +44 (0) 1753 849950  
FAX: +44 (0) 11753 577128

### Eudyna Devices International Srl

Via Teglio 8/2 - 20158  
Milano, Italy  
TEL: +39-02-3705 2921  
FAX: +39-02-3705 2920

### Eudyna Devices Asia Pte. Ltd.

Hong Kong Branch  
Suite 1906B, Tower 6, China Hong  
Kong City  
33 Canton Road, Tsim sha tsui,  
Kowloon  
Hong Kong  
TEL: +852-2377-0227  
FAX: +852-2377-3921

### Eudyna Devices Inc.

1000 Kamisukiahara, showa-cho  
Nakakomagun, Yamanashi  
409-3883, Japan  
(Kokubo Industrial Park)  
TEL +81-55-275-4411  
FAX +81-55-275-9461

### Sales Division

1, Kanai-cho, Sakae-ku  
Yokohama, 244-0845, Japan  
TEL +81-45-853-8156  
FAX +81-45-853-8170

### CAUTION

- Eudyna Devices Inc. products contain gallium arsenide (GaAs) which can be hazardous to the human body and the environment. For safety, observe the following procedures:
- Do not put these products into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by products are dangerous to the human body if inhaled, ingested, or swallowed.
- Observe government laws and company regulations when discarding this product. This product must be discarded in accordance with methods specified by applicable hazardous waste procedures.

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